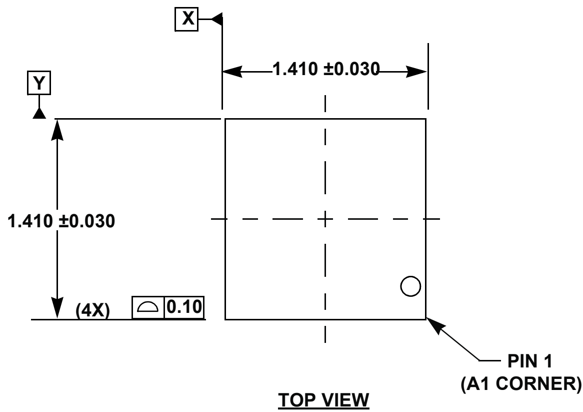
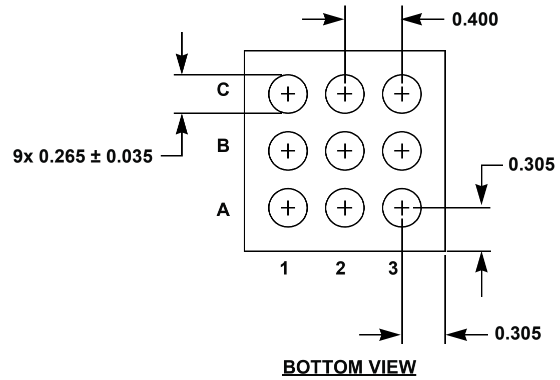
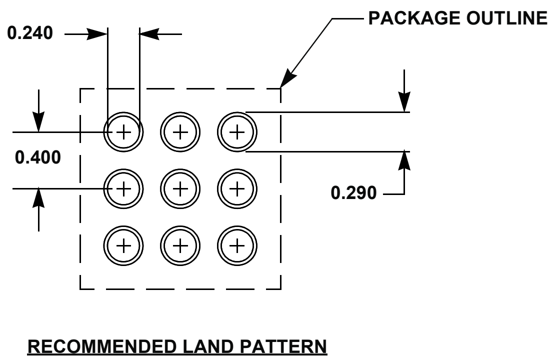
Package Outline Drawing

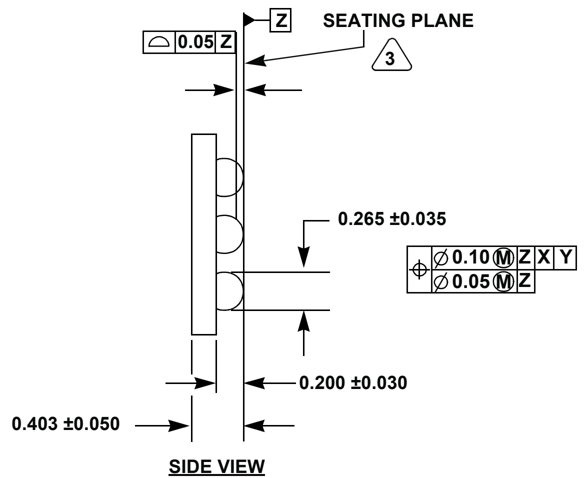
W3x3.9F

9 BALL 3x3 ARRAY THIN WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)
Rev 0, 3/16









NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASMEY 14.5 - 1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per TB451.